2-146472-7 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 2-146472-7 PCB Mount Header, Vertical, Board-to-Board, 27 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 27

Number of Rows: 1

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Breakaway

Sealable	No		
Connector & Contact Terminates To	Printed Circuit Board		
Configuration Features			
Stackable	Yes		
PCB Mount Orientation	Vertical		
Number of Positions	27		
Number of Rows	1		
Board-to-Board Configuration	Parallel		
Electrical Characteristics			
Insulation Resistance	5000 MΩ		
Body Features			
Primary Product Color	Black		
Contact Features			
Contact Mating Area Length	8.38 mm[.33 in]		
Mating Square Post Dimension	.64 mm[.025 in]		

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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Layout	Inline
Contact Underplating Material Thickness	1.27 μm[50 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.38 μm[15 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	

Mechanical Attachment

Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Stack Height	17.78 mm[.7 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	

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Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Type	Package
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Not Compliant
EU ROHS Directive 2011/65/EU EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) SVHC > Threshold: Pb (13% in Component Part) Atticle Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Low Halogen - contains Br or Cl > 900

Halogen Content

Not Low Halogen - contains Br or Cl > 900

nr

ppm.

Solder Process Capability

Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

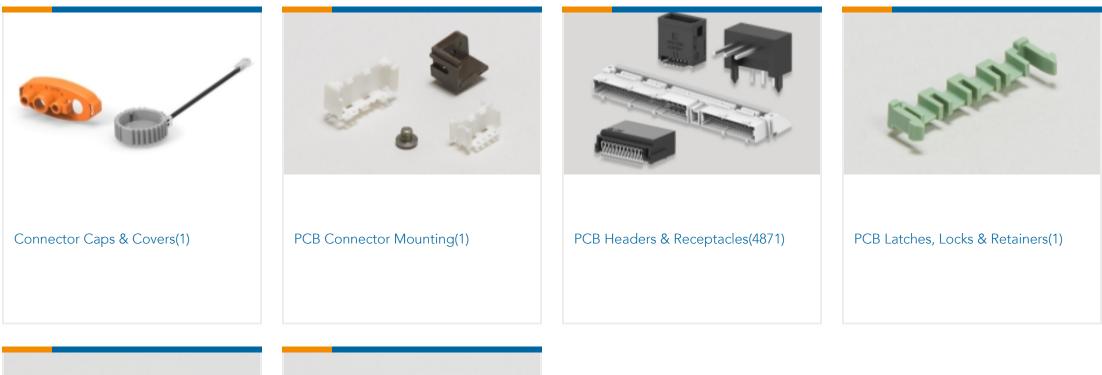
Compatible Parts

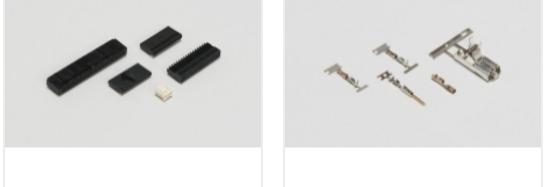
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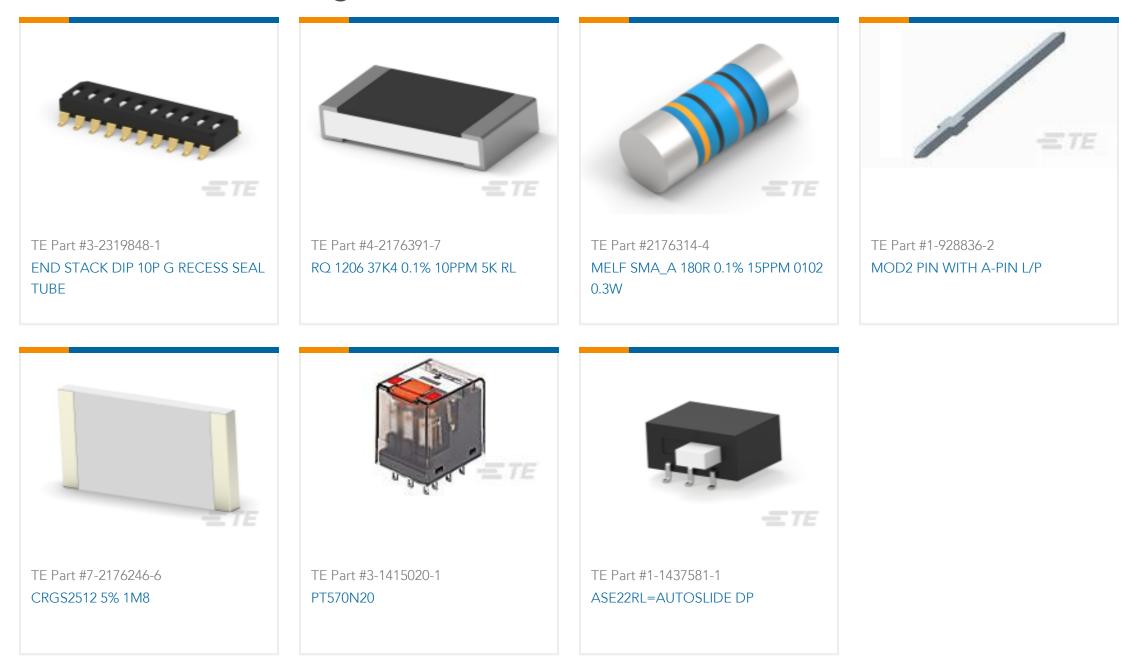
Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(64)
& Housings(5)	

Customers Also Bought



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Documents

Product Drawings 27 MODII HDR SRST UNSHRD STKG

English

Datasheets & Catalog Pages AMPMODU Interconnetion System

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